

DATA SHEET

PCA82C251

CAN transceiver for 24 V systems

Product specification
Supersedes data of 1997 Mar 14
File under Integrated Circuits, IC18

2000 Jan 13

CAN transceiver for 24 V systems

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FEATURES

- Fully compatible with the "ISO 11898-24 V" standard
- Slope control to reduce RFI
- Thermally protected
- Short-circuit proof to battery and ground in 24 V powered systems
- Low-current standby mode
- An unpowered node does not disturb the bus lines
- At least 110 nodes can be connected
- High speed (up to 1 Mbaud)
- High immunity against electromagnetic interference.

GENERAL DESCRIPTION

The PCA82C251 is the interface between the CAN protocol controller and the physical bus. It is primarily intended for applications (up to 1 Mbaud) in trucks and buses. The device provides differential transmit capability to the bus and differential receive capability to the CAN controller.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		4.5	5.5	V
I_{CC}	supply current	standby mode	–	275	μ A
$1/t_{bit}$	maximum transmission speed	non-return-to-zero	1	–	Mbaud
V_{CAN}	CANH, CANL input/output voltage		–36	+36	V
V_{diff}	differential bus voltage		1.5	3.0	V
T_{amb}	ambient temperature		–40	+125	$^{\circ}$ C

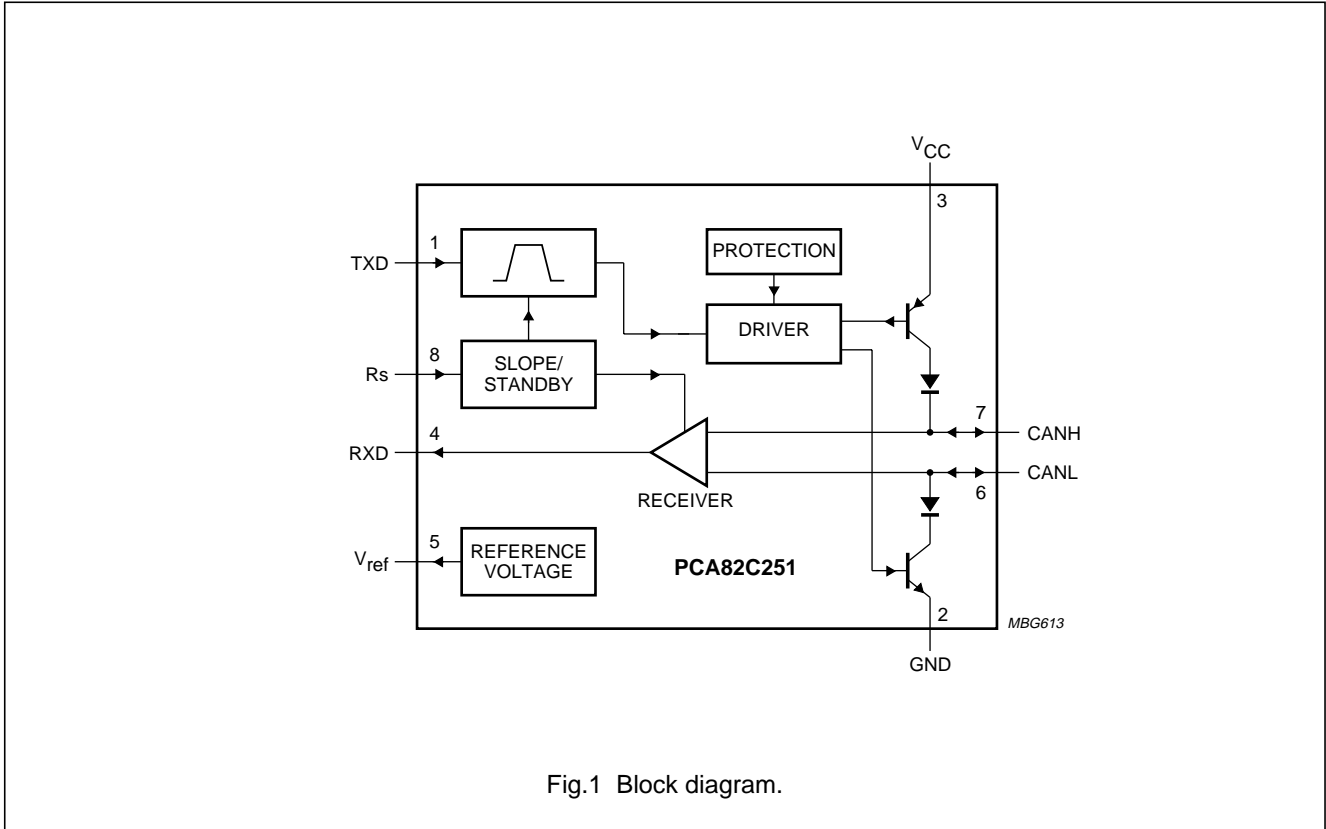
ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	CODE
PCA82C251	DIP8	plastic dual in-line package; 8 leads (300 mil)	SOT97-1
PCA82C251T	SO8	plastic small outline package; 8 leads body width 3.9 mm	SOT96-1
PCA82C251U	–	bare die; 2840 \times 1780 \times 380 μ m	–

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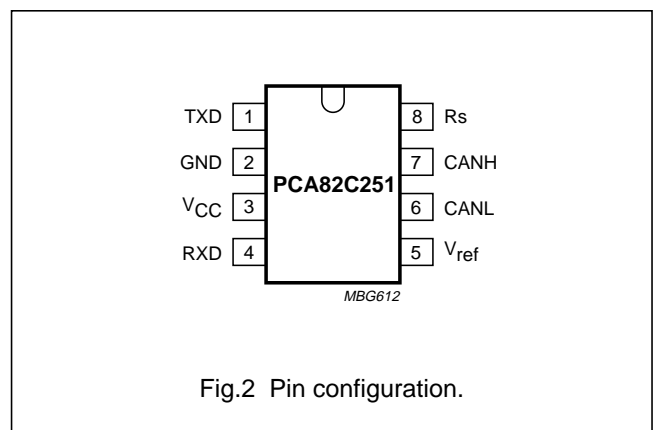
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BLOCK DIAGRAM



PINNING

SYMBOL	PIN	DESCRIPTION
TXD	1	transmit data input
GND	2	ground
V _{CC}	3	supply voltage
RXD	4	receive data output
V _{ref}	5	reference voltage output
CANL	6	LOW-level CAN voltage input/output
CANH	7	HIGH-level CAN voltage input/output
Rs	8	slope resistor input



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FUNCTIONAL DESCRIPTION

The PCA82C251 is the interface between the CAN protocol controller and the physical bus. It is primarily intended for applications up to 1 Mbaud in trucks and buses. The device provides differential transmit capability to the bus and differential receive capability to the CAN controller. It is fully compatible with the "ISO 11898-24 V" standard.

A current limiting circuit protects the transmitter output stage against short-circuit to positive and negative battery voltage. Although the power dissipation is increased during this fault condition, this feature will prevent destruction of the transmitter output stage.

If the junction temperature exceeds a value of approximately 160 °C, the limiting current of both transmitter outputs is decreased. Because the transmitter is responsible for the major part of the power dissipation, this will result in a reduced power dissipation and hence a lower chip temperature. All other parts of the IC will remain operating. The thermal protection is particularly needed when a bus line is short-circuited.

The CANH and CANL lines are also protected against electrical transients which may occur in an automotive environment.

Pin 8 (Rs) allows three different modes of operation to be selected: high-speed, slope control or standby.

For high-speed operation, the transmitter output transistors are simply switched on and off as fast as possible. In this mode, no measures are taken to limit the rise and fall slope. Use of a shielded cable is recommended to avoid RFI problems. The high-speed mode is selected by connecting pin 8 to ground.

The slope control mode allows the use of an unshielded twisted pair or a parallel pair of wires as bus lines. To reduce RFI, the rise and fall slope should be limited. The rise and fall slope can be programmed with a resistor connected from pin 8 to ground. The slope is proportional to the current output at pin 8.

If a HIGH level is applied to pin 8, the circuit enters a low current standby mode. In this mode, the transmitter is switched off and the receiver is switched to a low current. If dominant bits are detected (differential bus voltage >0.9 V), RXD will be switched to a LOW level. The microcontroller should react to this condition by switching the transceiver back to normal operation (via pin 8). Because the receiver is slower in standby mode, the first message will be lost at higher bit rates.

Table 1 Truth table of the CAN transceiver

V _{CC}	TXD	CANH	CANL	BUS STATE	RXD
4.5 to 5.5 V	0	HIGH	LOW	dominant	0
4.5 to 5.5 V	1 (or floating)	floating	floating	recessive	1 ⁽²⁾
4.5 < V _{CC} < 5.5 V	X ⁽¹⁾	floating if V _{Rs} > 0.75V _{CC}	floating if V _{Rs} > 0.75V _{CC}	floating	1 ⁽²⁾
0 < V _{CC} < 4.5 V	floating	floating	floating	floating	X ⁽¹⁾

Notes

1. X = don't care.
2. If another bus node is transmitting a dominant bit, then RXD is logic 0.

Table 2 Pin Rs summary

CONDITION FORCED AT PIN Rs	MODE	RESULTING VOLTAGE OR CURRENT AT PIN Rs
V _{Rs} > 0.75V _{CC}	standby	-I _{Rs} < 10 μA
10 μA < -I _{Rs} < 200 μA	slope control	0.4V _{CC} < V _{Rs} < 0.6V _{CC}
V _{Rs} < 0.3V _{CC}	high-speed	-I _{Rs} < 500 μA

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); all voltages are referenced to pin 2; positive input current.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		-0.3	+7.0	V
V_n	DC voltage at pins 1, 4, 5 and 8		-0.3	$V_{CC} + 0.3$	V
V_6	DC voltage at pin 6 (CANL)	$0\text{ V} < V_{CC} < 5.5\text{ V}$; TXD HIGH or floating	-36	+36	V
		$0\text{ V} < V_{CC} < 5.5\text{ V}$; no time limit; note 1	-36	+36	V
		$0\text{ V} < V_{CC} < 5.5\text{ V}$; no time limit; note 2	-36	+36	V
V_7	DC voltage at pin 7 (CANH)	$0\text{ V} < V_{CC} < 5.5\text{ V}$; no time limit	-36	+36	V
V_{tr}	transient voltage on pins 6 and 7	see Fig.8	-200	+200	V
T_{stg}	storage temperature		-55	+150	°C
T_{amb}	ambient temperature		-40	+125	°C
T_{vj}	virtual junction temperature	note 3	-40	+150	°C
V_{esd}	electrostatic discharge voltage	note 4	-2500	+2500	V
		note 5	-250	+250	V

Notes

- TXD is LOW. Short-circuit protection provided for slew rates up to $5\text{ V}/\mu\text{s}$ for voltages above +30 V.
- Short-circuit applied when TXD is HIGH, followed by TXD switched to LOW.
- In accordance with "IEC 60747-1". An alternative definition of virtual junction temperature is: $T_{vj} = T_{amb} + P_d \times R_{th(vj-a)}$, where $R_{th(vj-a)}$ is a fixed value to be used for the calculation of T_{vj} . The rating for T_{vj} limits the allowable combinations of power dissipation (P_d) and ambient temperature (T_{amb}).
- Classification A: human body model; C = 100 pF; R = 1500 Ω ; V = $\pm 2500\text{ V}$.
- Classification B: machine model; C = 200 pF; R = 0 Ω ; V = $\pm 250\text{ V}$.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		
	PCA82C251		100	K/W
	PCA82C251T		160	K/W

QUALITY SPECIFICATION

According to "SNW-FQ-611 part E".

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CHARACTERISTICS

$V_{CC} = 4.5$ to 5.5 V; $T_{amb} = -40$ to $+125$ °C; $R_L = 60$ Ω; $I_b > -10$ μA; unless otherwise specified; all voltages referenced to ground (pin 2); positive input current; all parameters are guaranteed over the ambient temperature range by design, but only 100% tested at $+25$ °C.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply						
I_3	supply current	dominant; $V_1 = 1$ V; $V_{CC} < 5.1$ V	–	–	78	mA
		dominant; $V_1 = 1$ V; $V_{CC} < 5.25$ V	–	–	80	mA
		dominant; $V_1 = 1$ V; $V_{CC} < 5.5$ V	–	–	85	mA
		recessive; $V_1 = 4$ V; $R_8 = 47$ kΩ	–	–	10	mA
		standby; note 1	–	–	275	μA
DC bus transmitter						
V_{IH}	HIGH-level input voltage	output recessive	$0.7V_{CC}$	–	$V_{CC} + 0.3$	V
V_{IL}	LOW-level input voltage	output dominant	–0.3	–	$0.3V_{CC}$	V
I_{IH}	HIGH-level input current	$V_1 = 4$ V	–200	–	+30	μA
I_{IL}	LOW-level input current	$V_1 = 1$ V	–100	–	–600	μA
$V_{6,7}$	recessive bus voltage	$V_1 = 4$ V; no load	2.0	–	3.0	V
I_{LO}	off-state output leakage current	-2 V < (V_6, V_7) < 7 V	–2	–	+2	mA
		-5 V < (V_6, V_7) < 36 V	–10	–	+10	mA
V_7	CANH output voltage	$V_1 = 1$ V; $V_{CC} = 4.75$ to 5.5 V	3.0	–	4.5	V
		$V_1 = 1$ V; $V_{CC} = 4.5$ to 4.75 V	2.75	–	4.5	V
V_6	CANL output voltage	$V_1 = 1$ V	0.5	–	2.0	V
$\Delta V_{6,7}$	difference between output voltage at pins 6 and 7	$V_1 = 1$ V	1.5	–	3.0	V
		$V_1 = 1$ V; $R_L = 45$ Ω	1.5	–	–	V
		$V_1 = 4$ V; no load	–500	–	+50	mV
I_{sc7}	short-circuit CANH current	$V_7 = -5$ V	–	–	–200	mA
		$V_7 = -36$ V	–	–100	–	mA
I_{sc6}	short-circuit CANL current	$V_6 = 36$ V	–	–	200	mA
DC bus receiver [$V_1 = 4$ V; pins 6 and 7 externally driven; -2 V < (V_6, V_7) < 7 V; unless otherwise specified]						
$V_{diff(r)}$	differential input voltage (recessive)	note 2	–1.0	–	+0.5	V
		-7 V < (V_6, V_7) < 12 V; note 2	–1.0	–	+0.4	V
$V_{diff(d)}$	differential input voltage (dominant)		0.9	–	5.0	V
		-7 V < (V_6, V_7) < 12 V; not standby mode	1.0	–	5.0	V
		standby mode	0.97	–	5.0	V
		standby mode; $V_{CC} = 4.5$ to 5.10 V	0.91	–	5.0	V
$V_{diff(hys)}$	differential input hysteresis	see Fig.5	–	150	–	mV

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{OH}	HIGH-level output voltage (pin 4)	I ₄ = -100 μA	0.8V _{CC}	–	V _{CC}	V
V _{OL}	LOW-level output voltage (pin 4)	I ₄ = 1 mA	0	–	0.2V _{CC}	V
		I ₄ = 10 mA	0	–	1.5	V
R _i	CANH, CANL input resistance		5	–	25	kΩ
R _{diff}	differential input resistance		20	–	100	kΩ
Reference output						
V _{ref}	reference output voltage	V ₈ = 1 V; I ₅ < 50 μA	0.45V _{CC}	–	0.55V _{CC}	V
		V ₈ = 4 V; I ₅ < 5 μA	0.4V _{CC}	–	0.6V _{CC}	V
Timing (R _L = 60 Ω; C _L = 100 pF; unless otherwise specified. See Figs 3 and 4)						
t _{bit}	minimum bit time	R ₈ = 0 Ω	–	–	1	μs
t _{onTXD}	delay TXD to bus active	R ₈ = 0 Ω	–	–	50	ns
t _{offTXD}	delay TXD to bus inactive	R ₈ = 0 Ω	–	40	80	ns
t _{onRXD}	delay TXD to receiver active	R ₈ = 0 Ω	–	55	120	ns
t _{offRXD}	delay TXD to receiver inactive	R ₈ = 0 Ω; T _{amb} < +85 °C; V _{CC} = 4.5 to 5.1 V	–	80	150	ns
		R ₈ = 0 Ω; V _{CC} = 4.5 to 5.1 V	–	80	170	ns
		R ₈ = 0 Ω; T _{amb} < +85 °C	–	90	170	ns
		R ₈ = 0 Ω	–	90	190	ns
		R ₈ = 47 kΩ	–	290	400	ns
t _{onRXD}	delay TXD to receiver active	R ₈ = 47 kΩ	–	440	550	ns
SR	CANH, CANL slew rate	R ₈ = 47 kΩ	–	7	–	V/μs
t _{WAKE}	wake-up time from standby (via pin 8)	see Fig.6	–	–	20	μs
t _{dRXDL}	bus dominant to RXD LOW	V ₈ = 4 V; see Fig.7	–	–	3	μs
Standby/slope control (pin 8)						
V _{stb}	input voltage for standby mode		0.75V _{CC}	–	–	V
I _{slope}	slope control mode current		-10	–	-200	μA
V _{slope}	slope control mode voltage		0.4V _{CC}	–	0.6V _{CC}	V

Notes

- I₁ = I₄ = I₅ = 0 mA; 0 V < V₆ < V_{CC}; 0 V < V₇ < V_{CC}; V₈ = V_{CC}; T_{amb} < 90 °C.
- This is valid for the receiver in all modes: high-speed, slope control and standby.

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TEST AND APPLICATION INFORMATION

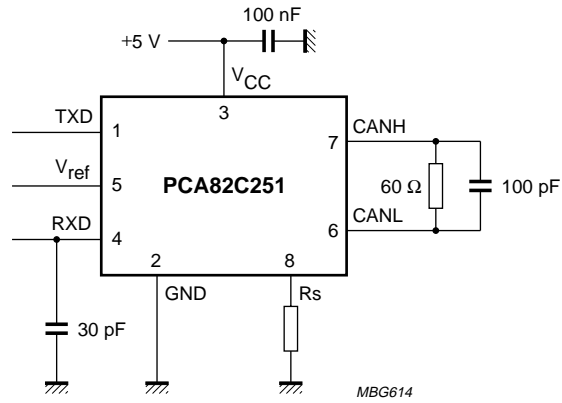


Fig.3 Test circuit for dynamic characteristics.

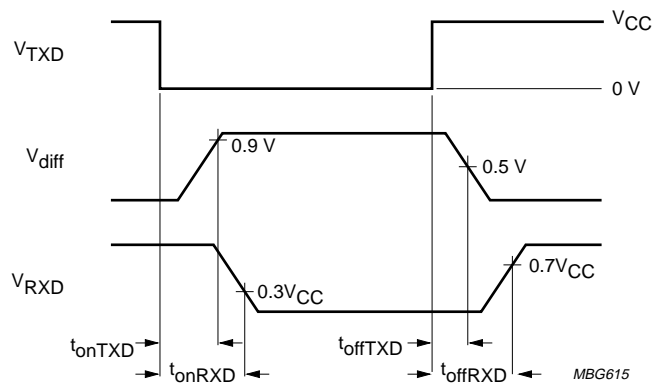


Fig.4 Timing diagram for dynamic characteristics.

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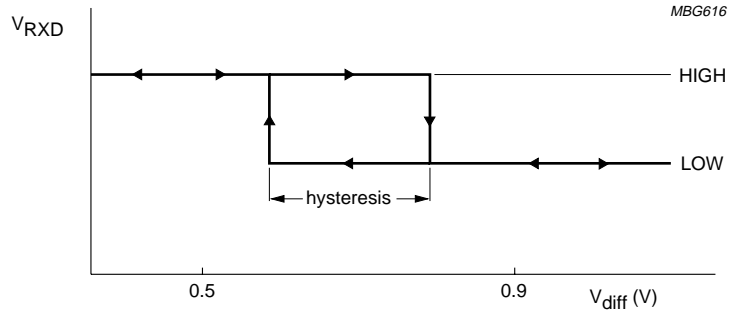
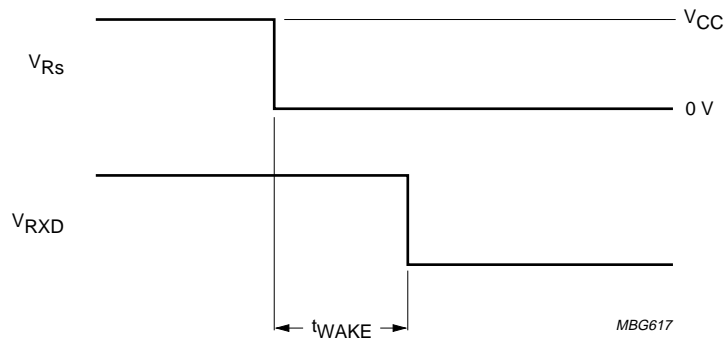
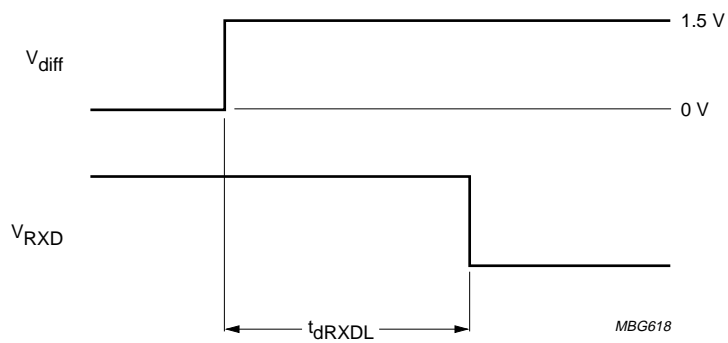


Fig.5 Hysteresis.



$V_{TXD} = 1\text{ V}$.

Fig.6 Timing diagram for wake up from standby.

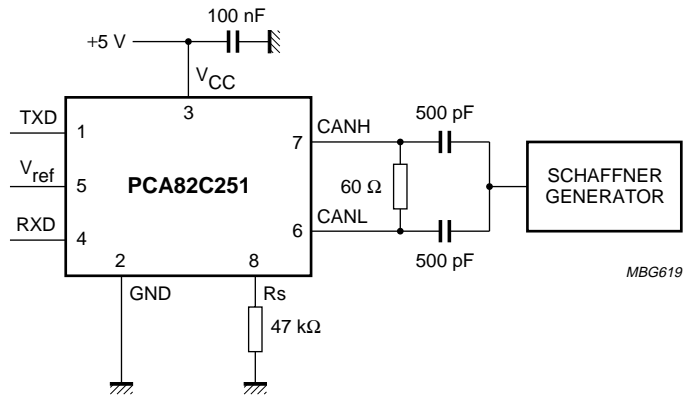


$V_{Rs} = 4\text{ V}; V_{TXD} = 4\text{ V}$.

Fig.7 Timing diagram for bus dominant to RXD low.

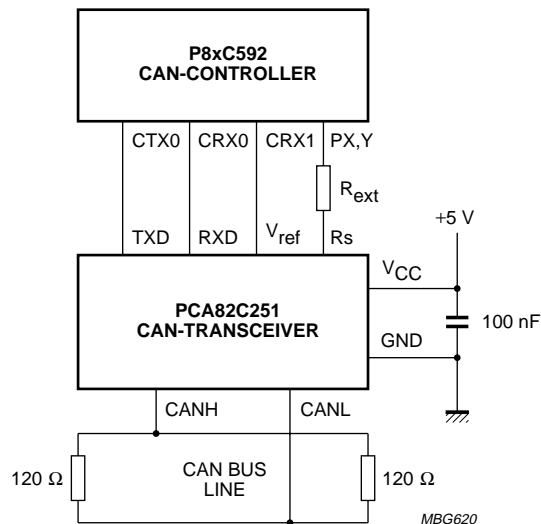
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The waveforms of the applied transients shall be in accordance with "ISO 7637 part 1", test pulses 1, 2, 3a and 3b.

Fig.8 Test circuit for automotive transients.



- (1) The output control register of the P8xC592 should be programmed to 1AH (push-pull operation, dominant = LOW).
- (2) If no slope control is desired: $R_{ext} = 0$.

Fig.9 Application of the PCA82C251 CAN Transceiver.

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BONDING PAD LOCATIONS

SYMBOL	PAD	COORDINATES ⁽¹⁾	
		x	y
TXD	1	196	137
GND	2	1080	137
V _{CC}	3	1567	137
RXD	4	2644	137
V _{ref}	5	2644	1644
CANL	6	1490	1644
CANH	7	748	1644
Rs	8	200	1610

Note

1. All coordinates (μm) represent the position of the centre of each pad with respect to the bottom left-hand corner of the die (x/y = 0).

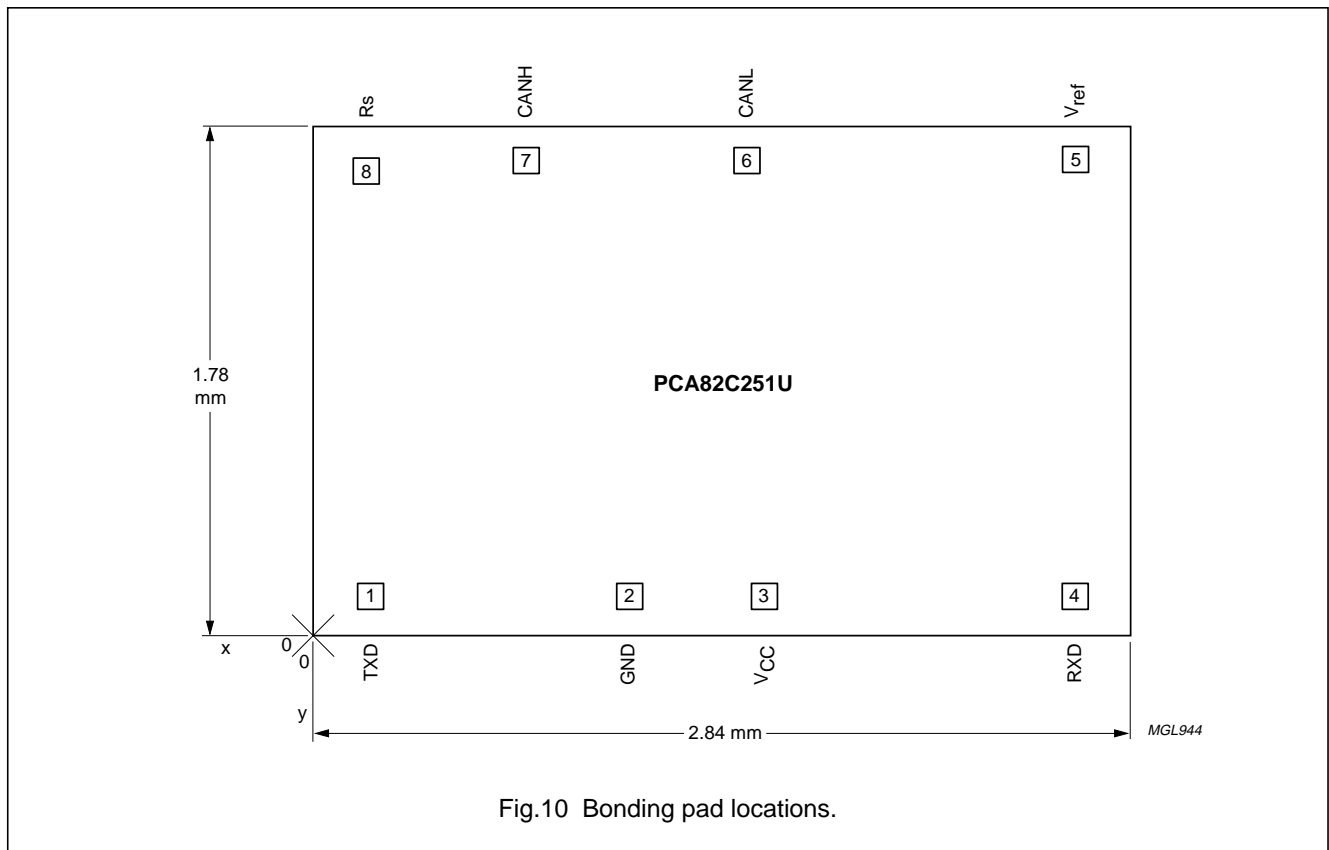


Fig.10 Bonding pad locations.

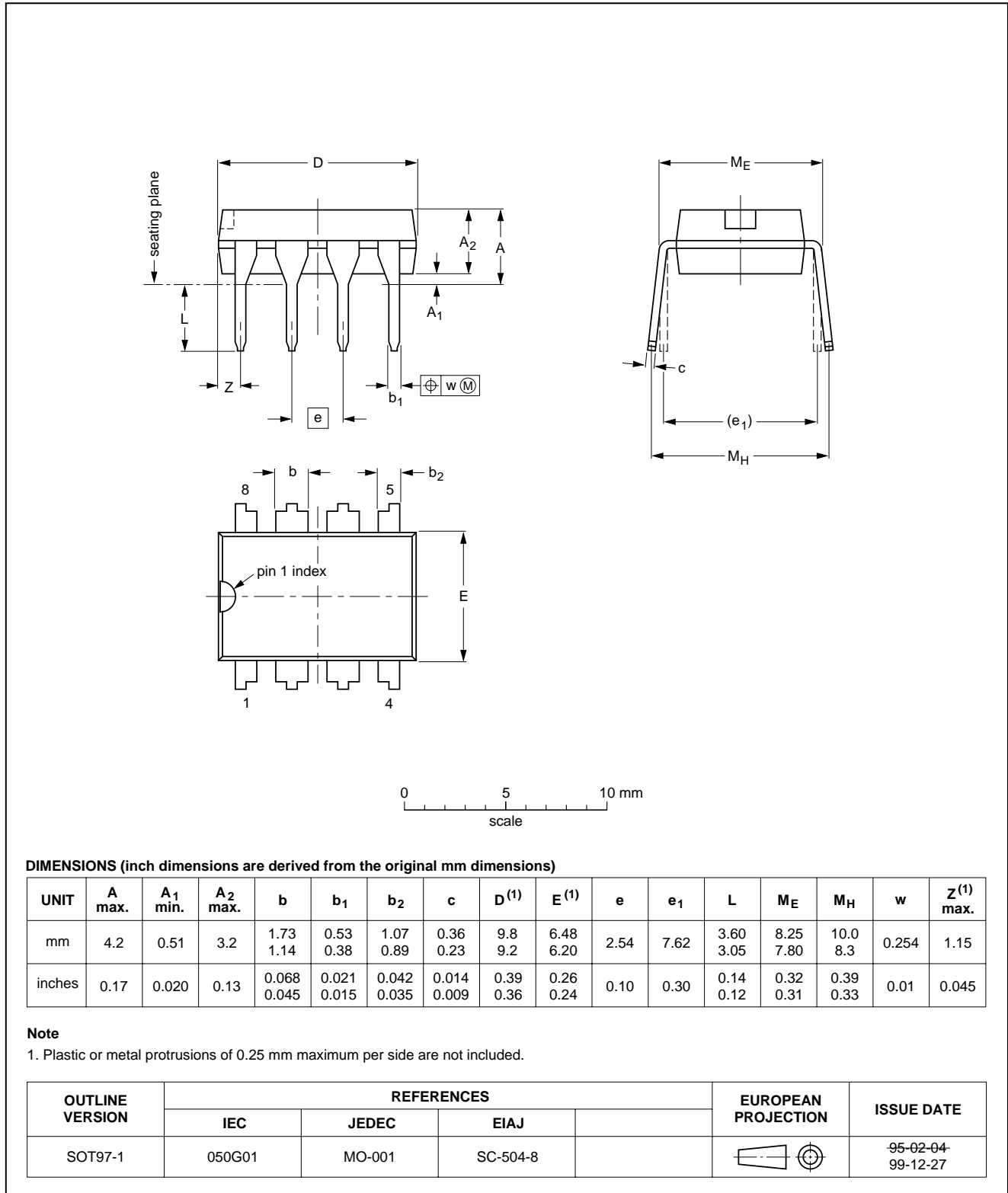
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PACKAGE OUTLINES

DIP8: plastic dual in-line package; 8 leads (300 mil)

SOT97-1

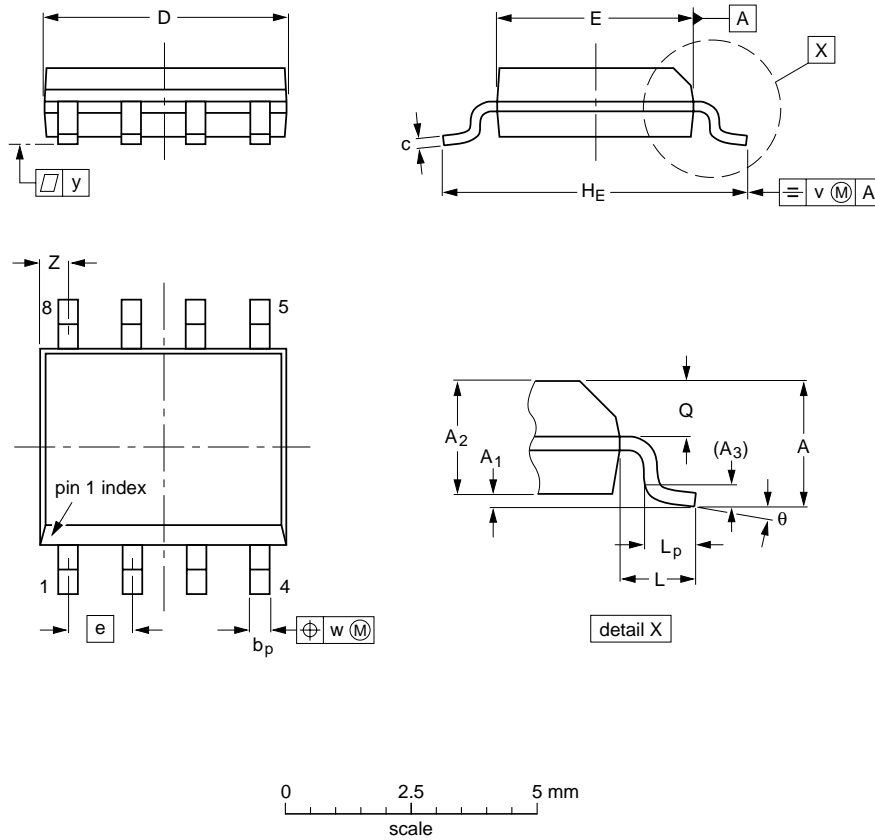


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S08: plastic small outline package; 8 leads; body width 3.9 mm

SOT96-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT96-1	076E03	MS-012				97-05-22 99-12-27

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SOLDERING

Introduction

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mount components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

Through-hole mount packages

SOLDERING BY DIPPING OR BY SOLDER WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joints for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg(max)}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

MANUAL SOLDERING

Apply the soldering iron (24 V or less) to the lead(s) of the package, either below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

Surface mount packages

REFLOW SOLDERING

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

WAVE SOLDERING

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

MANUAL SOLDERING

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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Suitability of IC packages for wave, reflow and dipping soldering methods

MOUNTING	PACKAGE	SOLDERING METHOD		
		WAVE	REFLOW ⁽¹⁾	DIPPING
Through-hole mount	DBS, DIP, HDIP, SDIP, SIL	suitable ⁽²⁾	–	suitable
Surface mount	BGA, LFBGA, SQFP, TFBGA	not suitable	suitable	–
	HBCC, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS	not suitable ⁽³⁾	suitable	–
	PLCC ⁽⁴⁾ , SO, SOJ	suitable	suitable	–
	LQFP, QFP, TQFP	not recommended ⁽⁴⁾⁽⁵⁾	suitable	–
	SSOP, TSSOP, VSO	not recommended ⁽⁶⁾	suitable	–

Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the “*Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods*”.
2. For SDIP packages, the longitudinal axis must be parallel to the transport direction of the printed-circuit board.
3. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
5. Wave soldering is only suitable for LQFP, QFP and TQFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
6. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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CAN transceiver for 24 V systems

PCA82C251

NOTES

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Datasheet



PCA82C251
(Product Specification)
13-Jan-00, 20 Pages, 95kB

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PCA82C251 - CAN transceiver for 24 V systems

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General description

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The PCA82C251 is the interface between the CAN protocol controller and the physical bus. It is primarily intended for applications (up to 1 Mbaud) in trucks and buses. The device provides differential transmit capability to the bus and differential receive capability to the CAN controller.

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Features

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- Fully compatible with the 'ISO 11898-24 V' standard
- Slope control to reduce RFI
- Thermally protected
- Short-circuit proof to battery and ground in 24 V powered systems
- Low-current standby mode
- An unpowered node does not disturb the bus lines
- At least 110 nodes can be connected
- High speed (up to 1 Mbaud)
- High immunity against electromagnetic interference.

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Products/packages

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Type number	Orderable part number	Ordering code (12NC)	Product status	Package	Packing	Marking	ECCN
PCA82C251T/YM	PCA82C251T/YM,112	9352 888 85112	Development	SOT96	Tube	Standard Marking	
PCA82C251T/YM	PCA82C251T/YM,118	9352 888 85118	Development	SOT96	Reel Pack, SMD, 13"	Standard Marking	





The variants in the table below are discontinued. See the table [Discontinued information](#) for more information.

Type number	Orderable part number	Ordering code (12NC)	Product status	Package	Packing	Marking	ECCN
PCA82C251/N3	PCA82C251/N3,112	9352 162 30112	Discontinued Replacement product	SOT97-1 (DIP8)	Tube	Standard Marking	
PCA82C251T/N3	PCA82C251T/N3,112	9351 960 20112	Discontinued Replacement product	SOT96	Tube	Standard Marking	
PCA82C251T/N3	PCA82C251T/N3,118	9351 960 20118	Discontinued Replacement product	SOT96	Reel Pack, SMD, 13"	Standard Marking	










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Quality/reliability/chemical content

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Type number	Orderable part number	Chemical content	RoHS	Leadfree conversion date	RHF	IFR (FIT)	MTBF (hours)	MSL
PCA82C251T/YM	PCA82C251T/YM,112	Not available	 	Always Pb-free				
PCA82C251T/YM	PCA82C251T/YM,118	Not available	 	Always Pb-free				

The variants in the table below are discontinued. See the table [Discontinued information](#) for more information.

Type number	Orderable part number	Chemical content	RoHS	Leadfree conversion date	RHF	IFR (FIT)	MTBF (hours)	MSL
PCA82C251/N3	PCA82C251/N3,112	PCA82C251_N3	 	Always Pb-free				
PCA82C251T/N3	PCA82C251T/N3,112	PCA82C251T_N3	 	week 8, 2005				
PCA82C251T/N3	PCA82C251T/N3,118	PCA82C251T_N3	 	week 8, 2005				

Quality and reliability disclaimer

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Pricing/ordering/availability

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Type number	Ordering code (12NC)	Orderable part number	Indicative price/unit (\$)	Region	Distributor	In stock	Order quantity	Inventory date	Buy online	Samples
PCA82C251T/YM	9352 888 85112	PCA82C251T/YM,112								not available
PCA82C251T/YM	9352 888 85118	PCA82C251T/YM,118								not available

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Discontinued information

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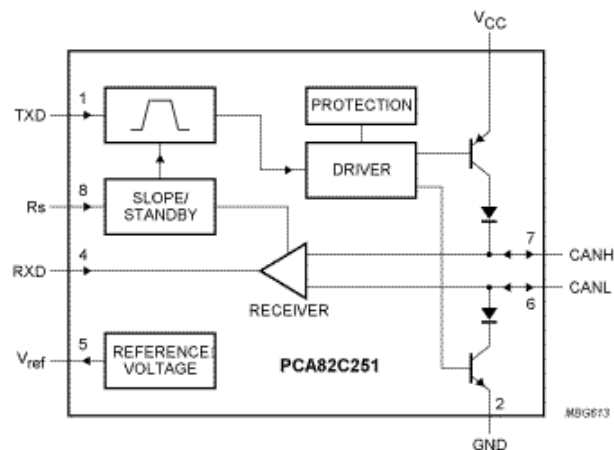
Type number	Ordering code (12NC)	Last-time buy date	Last-time delivery date	Replacement product	DN Notice	Status	Comments
PCA82C251/N3	935216230112	30-sep-09	31-dec-09	PCA82C251T TJA1042T	DN 62	Sole source product Standard availability Type number fully withdrawn	Standard End of Life.

PCA82C251T/N3	935196020112	31-dec-09	31-mrt-12	PCA82C251T/YM	DN 64	Sole source product Limited availability (check with your usual sales contact)	FAB ICN5 Closure. Refer to PCN200901053A dated January 21, 2009. Extended Last Time Delivery to 31.3.2012. Replacement type with new diffusion fab location only
PCA82C251T/N3	935196020118	31-dec-09	31-mrt-12	PCA82C251T/YM	DN 64	Sole source product Limited availability (check with your usual sales contact)	FAB ICN5 Closure. Refer to PCN200901053A dated January 21, 2009. Extended Last Time Delivery to 31.3.2012. Replacement type with new diffusion fab location only

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Block diagrams/pinning

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Design support

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Application Notes

- AN96116;PCA82C250/251 CAN Transceiver (1998-03-11)
- AN96116;PCA82C250/251 CAN Transceiver (1998-03-11)
- AN10211_2;TJA1040 high speed CAN transceiver (2006-11-10)
- AN00094_3;TJA1041/1041A high speed CAN transceiver (2006-11-08)
- AN00020_2;TJA1050 high speed CAN transceiver (2006-11-10)

Support Documents

- 75015744; High-speed CAN transceivers TJA104x, JA1050 and PCA82C25x (2006-09-01)
- 75016161; NXP Automotive networking solutions (2007-09-01)
- PCA82C250_251_TJA1040_TJA1050; Upgrading Note PCA82C250/251 -> TJA1040, TJA1050 (2001-11-20)

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Parametrics/similar products

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Type number	Package	Supply voltage	Application	Configuration	CATEGORY	FEATURES	FUNCTION	Operating temp.	No. of Pins	Package Material	Transceiver Type
-------------	---------	----------------	-------------	---------------	----------	----------	----------	-----------------	-------------	------------------	------------------

		(V)						(Cel)			
PCA82C251/N3	SOT97-1 (DIP8)	4.75 ~ 5.25	Control Devices	HS-CAN transceiver	transceiver	ISO11898-2 compliant, standby mode, for 24V systems	Transceivers	-40 ~ +125	8	DIL8, SO8, bare die	CAN Transceivers For 24 V Systems
PCA82C251T/N3	SOT96	4.75 ~ 5.25	Control Devices	HS-CAN transceiver	transceiver	ISO11898-2 compliant, standby mode, for 24V systems	Transceivers	-40 ~ +125	8	DIL8, SO8, bare die	CAN Transceivers For 24 V Systems

Similar products

PCA82C251 links to the similar products page containing an overview of products that are similar in function or related to the type number(s) as listed on this page. The similar products page includes products from the same catalog tree(s), relevant selection guides and products from the same functional category.

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